

Product Specification

200G QSFP56 to 2x 100G QSFP56 Active Optical Breakout Cable

PN:Q200-2Q100-A



Features

- Supporting 200Gbps to 2x100Gbps
- Available length range 1m~50m
- Active Optical Cable
- Data rates per channel 50Gbps
- Operating data rate 200Gbps
- Single +3.3V power supply
- Max power dissipation $\leq 4.5W$
- VCSEL Array Transmitter and PIN Array Receiver
- High-Density QSFP56 38-PIN Connector
- 4-Channel Full-Duplex Active Optical Cable
- Commercial temperature range 0°C to 70°C

Compliance

- Compliant with QSFP56 MSA
- Compliant with Electrical MSA SFF-8636
- Compliant with Mechanical MSA SFF-8665
- IEEE 802.3bj
- RoHS

Applications

- 200/50 Gigabit Ethernet
- Switches, servers, routers and HBA
- Data center cabling infrastructure
- High speed multi-channel parallel data connections

Description

The 200G-Q56-2Q-A is a high-efficiency Active Optical Cable (AOC) designed to enable flexible 200G-to-dual-100G network aggregation in QSFP-to-2xQSFP56 configurations, ideal for data center spine-leaf architectures and AI/ML cluster interconnects. Utilizing PAM4 modulation, it splits a 200Gb/s (4x53Gbps) QSFP interface into two independent 100Gb/s QSFP56 channels via multimode fiber, supporting distances up to 70m (OM4) with <5ns latency. Its integrated DSP-free design ensures plug-and-play deployment while maintaining backward compatibility with QSFP56 ecosystems. The cable consumes <8W per port and features robust EMI shielding, aligning with energy-efficient data center thermal budgets.

Optimized for port density and scalability, this AOC leverages QSFP56's compact form factor to deliver 1:2 breakout connectivity without sacrificing signal integrity. It supports Ethernet, InfiniBand, and RoCE protocols, enabling seamless integration into 200G/400G-ready networks while reducing fiber costs by 50% compared to discrete 100G links. Compliant with IEEE 802.3bs and CMIS 5.0 standards, it provides future-proof interoperability for hyperscale storage, HPC workloads, and distributed AI training clusters requiring deterministic low-latency performance.

Product performance Specifications

1、 Basic Product Characteristics

Parameter	Symbol	Min	Typ.	Max	Unit
Supply voltage	V _{CC}	-0.3	-	3.6	V
Data input voltage		-0.3	-	3.465	V
Control input voltage	V _I	-0.3	-	4.0	V
Damage threshold		3.4	-	-	dBm
Storage temperature	T _S	-40	-	85	°C
Supply Voltage	V _{CC}	3.135	-	3.465	V
Power dissipation (200G re-timing on all lanes)		-	4.35	4.55	W
Power dissipation (100G re-timing on all lanes)		-	2.5	2.75	W
Supply noise tolerance (10Hz-10MHz)		66	-	-	mVpp
Operating case temperature	T _{OC}	0	-	70	°C
Operating relative humidity	RH	5	-	85	%

2、 Product Optical and Electrical Characteristics

Parameter	Symbol	Min	Typ.	Max	Unit	Note
Transmitter						
Signaling Speed per Lane	PRBS31Q@26.5625Gbd PAM4				Gb/s	
Differential Input Impedance	Z _{IN}	90	100	110	Ω	
Center Wavelength	C	840	850	860	nm	
Differential Input Voltage	V _{IN}	-	900	-	mVpp	
Differential termination mismatch				10	%	
DC common mode voltage		350		2850	mV	
Receiver						
Signaling Speed per Lane	PRBS31Q@26.5625Gbd PAM4				Gb/s	
Center Wavelength	C	840	850	860	nm	
Differential Input Impedance				10	%	
Differential Input Voltage	Z _{out}	90	100	110	Ω	
Differential termination mismatch	V _{out}			900	mVpp	
DC common mode voltage		-350		2850	mV	
Error Bit Rate	BER			2.4E ⁻⁴		

Note1:PRBS31Q@26.5625Gbd PAM4

Recommended Host Board Power Supply Circuit

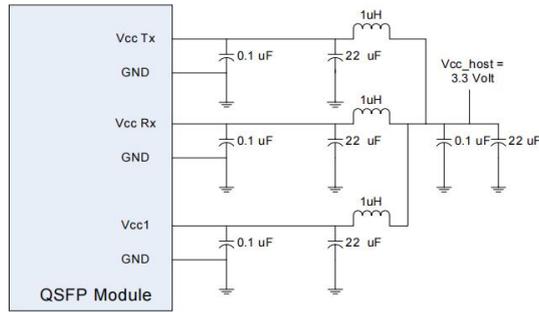


Figure 1: Recommended Host Board Power Supply Circuit

Recommended Interface Circuit

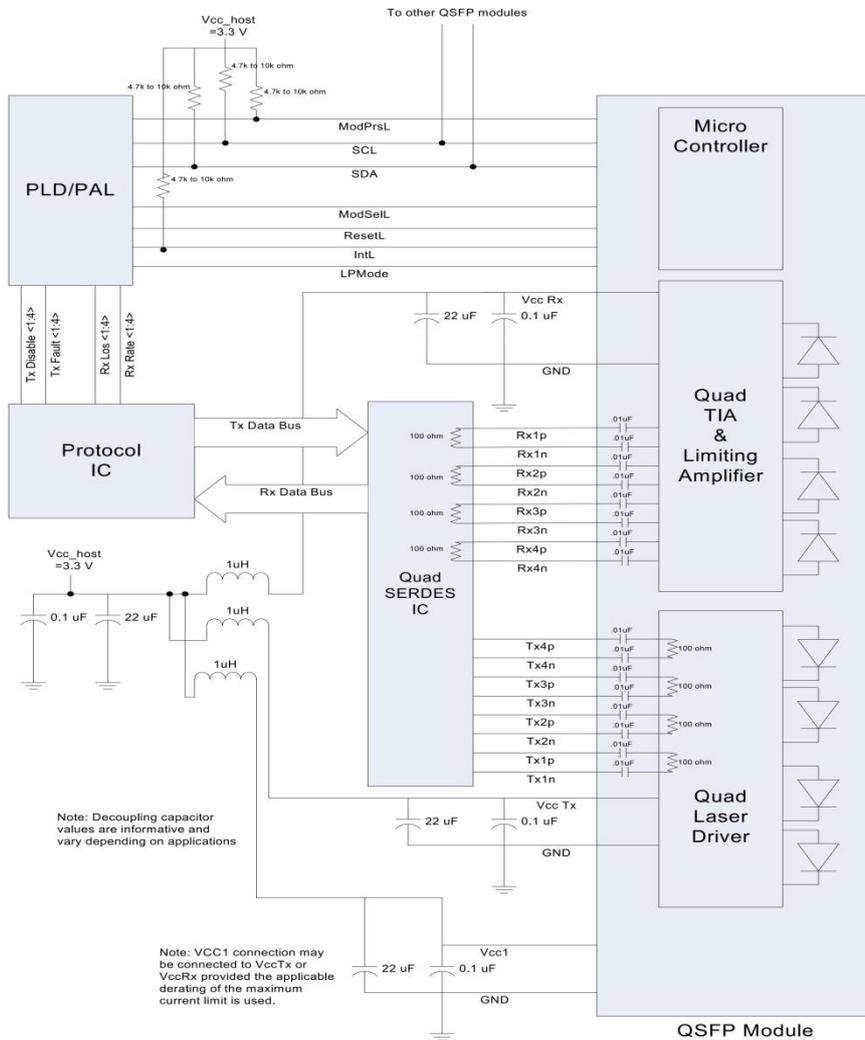


Figure 2: Recommended Interface Circuit

Pin-out Definition

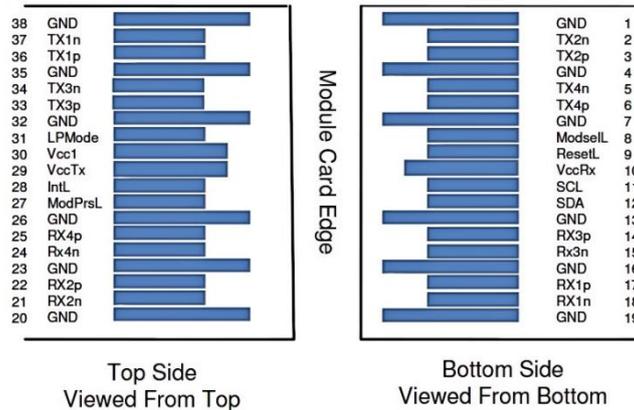


Figure3: Pin view

Pin Function Definitions

Pin	Logic	Symbol	Description	Note
1		GND	Ground	1
2	CML-I	Tx2n	Transmitter Inverted Data Input	3
3	CML-I	Tx2p	Transmitter Non-Inverted Data Input	3
4		GND	Ground	1
5	CML-I	Tx4n	Transmitter Inverted Data Input	3
6	CML-I	Tx4p	Transmitter Non-Inverted Data Input	3
7		GND	Ground	1
8	LVTTL-I	ModSelL	Module Select	4
9	LVTTL-I	ReSelL	Module Select	4
10		Vcc Rx	+3.3V Power Supply Receiver	2
11	LVC MOS-I/O	SCL	2-wire serial interface clock	4
12	LVC MOS-I/O	SDA	2-wire serial interface data	4
13		GND	Ground	1
14	CML-O	Rx3p	Receiver Non-Inverted Data Output	3
15	CML-O	Rx3n	Receiver Inverted Data Output	3
16		GND	Ground	1
17	CML-O	Rx1p	Receiver Non-Inverted Data Output	3
18	CML-O	Rx1n	Receiver Inverted Data Output	3
19		GND	Ground	1
20		GND	Ground	1
21	CML-O	Rx2n	Receiver Inverted Data Output	3
22	CML-O	Rx2p	Receiver Non-Inverted Data Output	3
23		GND	Ground	1
24	CML-O	Rx4n	Receiver Inverted Data Output	3

25	CML-O	Rx4p	Receiver Non-Inverted Data Output Ground	3
26		GND	Ground	1
27	LVTTL-O	ModPrsL	Module Present	4
28	LVTTL-O	IntL	Interrupt	4
29		Vcc Tx	+3.3V Power supply transmitter	2
30		Vcc1	+3.3V Power supply	2
31	LVTTL-I	LPMode	Low Power Mode	4
32		GND	Ground	1
33	CML-I	Tx3p	Transmitter Non-Inverted Data Input	3
34	CML-I	Tx3n	Transmitter Inverted Data Input	3
35		GND	Ground	1
36	CML-I	Tx1p	Transmitter Non-Inverted Data Input	3
37	CML-I	Tx1n	Transmitter Inverted Data Input	3
38		GND	Ground	1

Note1: GND is the symbol for signal and supply (power) common for the QSFP+ module. All are common within the QSFP+ module and all module voltages are referenced to this potential unless otherwise noted. Connect these directly to the host board signal-common ground plane.

Note2: Vcc Rx, Vcc1 and Vcc Tx are the receiver and transmitter power supplies and shall be applied concurrently. Requirements defined for the host side of the Host Edge Card Connector are listed in Table. Recommended host board power supply filtering is shown in Host board power supply circuit. Vcc Rx Vcc1 and Vcc Tx may be internally connected within the QSFP module in any combination. The connector pins are each rated for a maximum current of 500 mA.

Note3: High-speed signal interfaces require differential pairs (e.g. TX1+/TX1-) with tightly matched impedances (typically 100Ω).

Note4: The management and control signals are based on LVTTL level logic and are used for functions such as module selection and reset.

Monitoring Specification

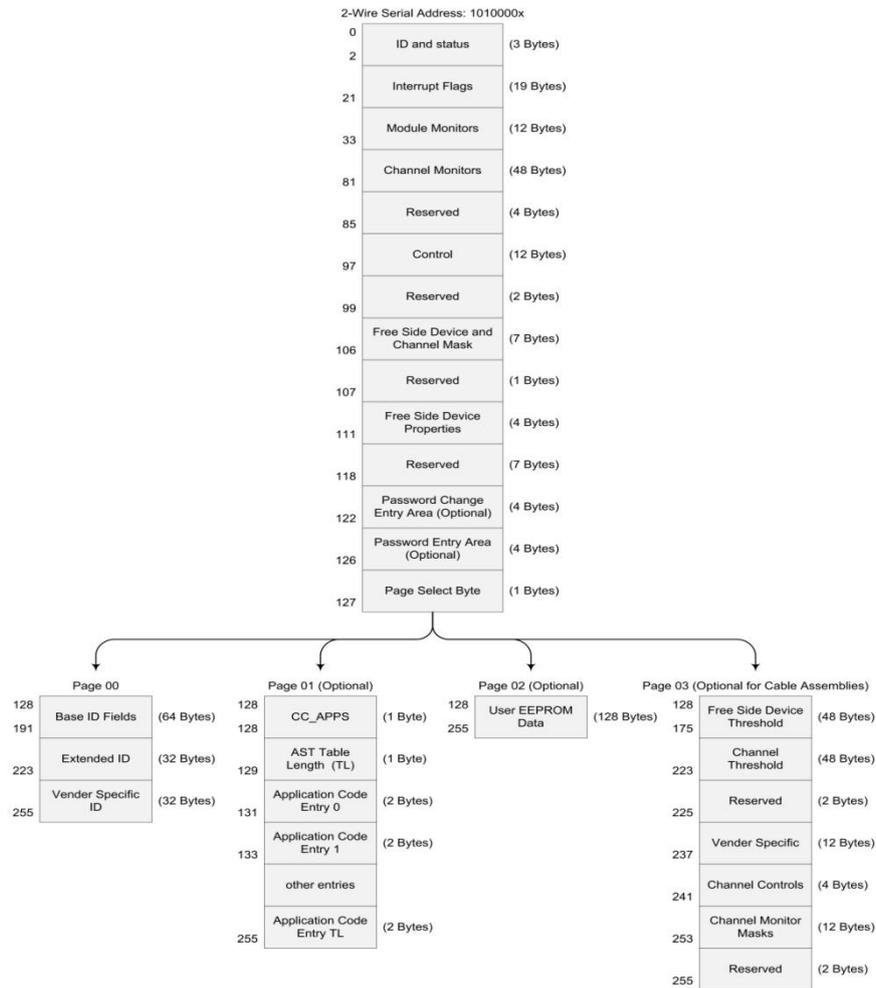


Figure4:QSFP Memory map

Memory map Table

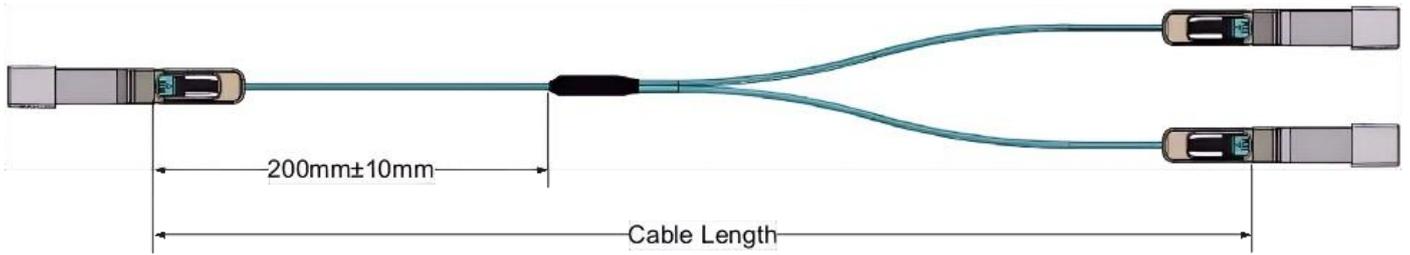
Byte	Unit	Name	Description
Lower Page 00h			
0	1	Identifier	Type of transceiver,Page 00h Byte 0 and Page 00h Byte 128 shall contain the same parameter values.
1	1	Status	Revision Compliance
2	1	Status	Status indicators
3-21	19	Interrupt Flags	Consist of interrupt flags for LOS, Tx Fault, warnings and alarms. The non-asserted state shall be 0b.
22	1	Temperature MSB	Internally measured temperature (MSB)
23	1	Temperature LSB	Internally measured temperature (LSB)
24-25	2	Reserved	Reserved

26	1	Supply Voltage MSB	Internally measured supply voltage (MSB)
27	1	Supply Voltage LSB	Internally measured supply voltage (LSB)
28-29	2	Reserved	Reserved
30-33	4	Vendor Specific	Vendor Specific
34	1	Rx1 Power MSB	Internally measured Rx1 input power
35	1	Rx1 Power LSB	
36	1	Rx2 Power MSB	Internally measured Rx2 input power
37	1	Rx2 Power LSB	
38	1	Rx3 Power MSB	Internally measured Rx3 input power
39	1	Rx3 Power LSB	
40	1	Rx4 Power MSB	Internally measured Rx4 input power
41	1	Rx4 Power LSB	
42	1	Tx1 Bias MSB	Internally measured Tx1 bias
43	1	Tx1 Bias LSB	
44	1	Tx2 Bias MSB	Internally measured Tx2 bias
45	1	Tx2 Bias LSB	
46	1	Tx3 Bias MSB	Internally measured Tx3 bias
47	1	Tx3 Bias LSB	
48	1	Tx4 Bias MSB	Internally measured Tx4 bias
49	1	Tx4 Bias LSB	
50	1	Tx1 Power MSB	Internally measured Tx1 Power
51	1	Tx1 Power LSB	
52	1	Tx2 Power MSB	Internally measured Tx2 Power
53	1	Tx2 Power LSB	
54	1	Tx3 Power MSB	Internally measured Tx3 Power
55	1	Tx3 Power LSB	
56	1	Tx4 Power MSB	Internally measured Tx4 Power
57	1	Tx4 Power LSB	
58-65	8	Reserved	Reserved channel monitor set 4
66-73	8	Reserved	Reserved channel monitor set 5
74-81	8	Vendor Specific	Vendor Specific
82-85	4	Reserved	Reserved
86-99	14	Control	Control
100-106	7	Free Side Device and Channel Masks	Free Side Device and Channel Masks
107-110	4	Free Side Device Properties	Free Side Device Properties
111-112	2	Assigned for use by PCI Express	Used for:
			- The PCI Express External Cable Specification
			- The PCI Express OCuLink Specification
113-117	4	Free Side Device Properties	Free Side Device Properties
118	1	Reserved	Reserved
119-122	4	Password Change Entry Area	Password Change Entry Area

123-126	4	Password Entry Area	Password Entry Area
127	1	Page Select Byte	Page Select Byte
Upper Page 00h			
128	1	Identifier	Identifier Type of free side device.(See SFF-8024 Transceiver Management)
129	1	Ext. Identifier	Extended Identifier of free side device. Includes power classes, CLEI codes, CDR capability.
130	1	Connector Type	Code for media connector type. (See SFF-8024 Transceiver Management)
131-138	8	Specification Compliance	Code for electronic or optical compatibility.
139	1	Encoding	Code for serial encoding algorithm. (See SFF-8024 Transceiver Management)
140	1	Signaling rate, nominal	Nominal signaling rate, units of 100 MBd. For rate > 25.4 GBd, set this to FFh and use Byte 222.
141	1	Extended Rate Select Compliance	Tags for extended rate select compliance.
142	1	Length (SMF)	Link length supported at the signaling rate in byte 140 or page 00h byte 222, for SMF fiber in km *. A value of 1 shall be used for reaches from 0 to 1 km.
143	1	Length (OM3 50 um)	Link length supported at the signaling rate in byte 140 or page 00h byte 222, for EBW 50/125 um fiber (OM3), units of 2 m *
144	1	Length (OM2 50 um)	Link length supported at the signaling rate in byte 140 or page 00h byte 222, for 50/125 um fiber (OM2), units of 1 m *
145	1	Length (OM1 62.5 um) or Copper	Link length supported at the signaling rate in byte 140 or page 00h byte 222, for 62.5/125 um fiber (OM1), units of 1 m *, or copper cable attenuation in dB at 25.78 GHz.
		Cable Attenuation	
146	1	Length (passive copper or active cable or OM4 50 um)	Length of passive or active cable assembly (units of 1 m) or link length supported at the signaling rate in byte 140 or page 00h byte 222, for OM4 50/125 um fiber (units of 2 m) as indicated by Byte 147. See 6.3.12.
147	1	Device technology	Device technology
148-163	16	Vendor name	Free side device vendor name (ASCII)
164	1	Extended Module	Extended Module codes for InfiniBand.
165-167	3	Vendor OUI	Free side device vendor IEEE company ID.
168-183	16	Vendor PN	Part number provided by free side device vendor(ASCII)
184-185	2	Vendor rev	Revision level for part number provided by the vendor(ASCII)
186-187	2	Wavelength or Copper Cable Attenuation	Nominal laser wavelength (wavelength=value/20 in nm) or copper cable attenuation in dB at 2.5 GHz (Byte 186) and 5.0 GHz (Byte 187)
188-189	2	Wavelength tolerance or Copper Cable Attenuation	The range of laser wavelength (+/- value) from nominal wavelength. (wavelength Tol. =value/200 in nm) or copper cable attenuation in dB at 7.0 GHz (Byte 188) and 12.9 GHz (Byte 189)
190	1	Max case temp	Maximum case temperature

191	1	CC_BASE	Check code for base ID fields (Bytes 128-190)
192	1	Link codes	Extended Specification Compliance Codes (See SFF-8024)
193-195	3	Options	Optional features implemented.
196-211	16	Vendor SN	Serial number provided by vendor.(ASCII)
212-219	8	Date Code	Vendor's manufacturing date code.
220	1	Diagnostic Monitoring Type	Indicates which type of diagnostic monitoring is implemented (if any) in the free side device. Bit 1,0 Reserved.
221	1	Enhanced Options	Indicates which optional enhanced features are implemented in the free side device.
222	1	CC_EXT	Check code for the Extended ID Fields (Bytes 192-222)
224-255	32	Vendor Specific	Vendor Specific EEPROM

MechanicalDimension



Note:

- Diameter: 3mm
- Minimum bend radius:30mm
- Cable color:Orange(OM2),Aqua(OM3),Magenta(OM4)
- When $L \leq 1m$, the tolerance is +5cm
- When $1m \leq L \leq 4.5m$, the tolerance is +15cm
- When $5m \leq L \leq 14.5m$, the tolerance is +30cm
- When $L \geq 15m$, the tolerance is +2% m

Waring:

- The transceiver optics is supplied with a dust cover. This plug protects the transceiver optics during standard manufacturing processes by preventing contamination from air borne particles.It is recommended that the dust cover remain in the transceiver whenever an optical fiber connector is not inserted.
- Handling Precautions: This device is susceptible to damage as a result of electrostatic discharge (ESD). A static free environment is highly recommended. Follow guidelines according to proper ESD procedures.
- Laser Safety: Radiation emitted by laser devices can be dangerous to human eyes. Avoid eye exposure to direct or indirect radiation.